



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

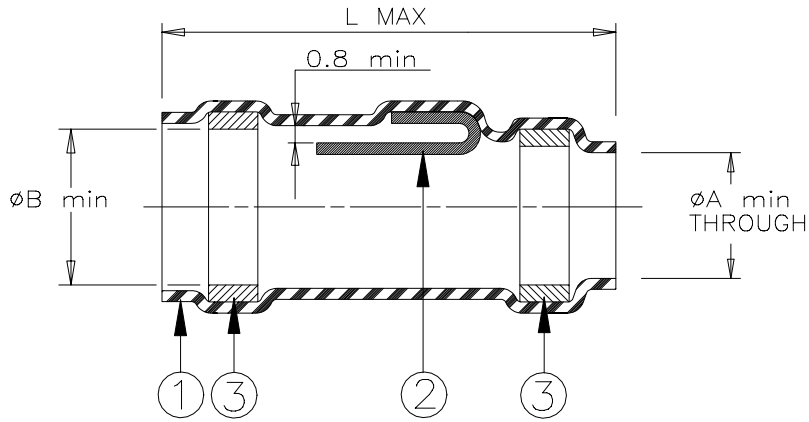
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SPECIFICATION CONTROL DRAWING



Product Revision		Product Dimensions					Cable Dimensions			
Product Name		L max	øA min	øB min	øE max	øC max	øD min	øF min	H±0.5 (H±0.02)	G±0.5 (G±0.02)
B-013-10	H	17.2 (0.675)	2.6 (0.085)	3.9 (0.155)	2.6 (0.100)	3.9 (0.155)	1.4 (0.055)	1.2 (0.045)	5.5 (0.215)	7.0 (0.275)
B-013-11	E	17.2 (0.675)	4.8 (0.190)	5.9 (0.230)	4.8 (0.190)	5.9 (0.230)	2.5 (0.100)	1.7 (0.065)	5.5 (0.215)	7.0 (0.275)
B-013-12	F	20.8 (0.820)	6.8 (0.270)	8.3 (0.325)	6.8 (0.270)	8.3 (0.325)	4.1 (0.160)	3.0 (0.120)	5.5 (0.215)	7.0 (0.275)
B-013-13	F	24.5 (0.965)	10 (0.395)	11.6 (0.455)	10 (0.395)	11.6 (0.455)	6.5 (0.255)	4.5 (0.175)	8.0 (0.315)	9.5 (0.375)

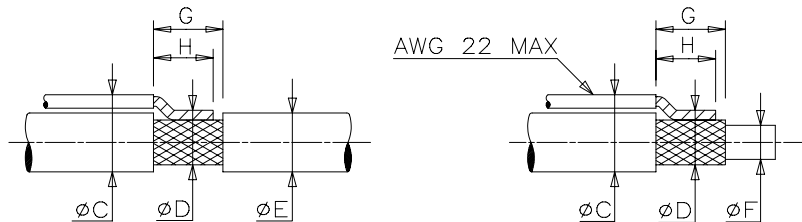
MATERIALS

- INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
- SOLDER PREFORM WITH FLUX:
 SOLDER: TYPE Sn96 per ANSI-J-STD-006.
 FLUX: TYPE ROM1 per ANSI-J-STD-004.
- MELTABLE SEALING RINGS: Thermally stabilized thermoplastic. Color: blue.

APPLICATION

- These controlled soldering devices are designed for termination of a nickel plated copper shield on cables having an insulation rated for at least +150°C.
- Temperature range: -55°C to +175°C with excursion to 200°C.
- When installed per Raychem Process Standard, RCPS-100-70 or Aerospace Process Standard, IPDA 83-16, assemblies will meet those requirements of Raychem Specifications RT-1404.

For best results, prepare the cable as shown:



Raychem Interconnect <small>a division of tyco ELECTRONICS</small> 300 Constitution Drive Menlo Park, CA 94025, USA		THERMOFIT DEVICES		TITLE: SOLDERSLEEVE DEVICE WITH LOCALIZED SOLDER HIGH TEMPERATURE			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.				DOCUMENT NO.: B-013-1X			
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	Raychem reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		DCR NUMBER: D000155	REPLACES: D980890		
DRAWN BY: M. FORONDA	DATE: 19-April-00	PROD. REV.: SEE TABLE	DOC. ISSUE: 17	SCALE: None	SIZE: A	SHEET: 1 of 1	

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